



Product Change Notification / JAON-23SJYM687

Date:

01-Mar-2021

Product Category:

Smart Energy SOC

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4574 Initial Notice: Qualification of ASEM as an additional assembly site for ATSAM4C32CA-AU and ATSAM4C32CA-AUR catalog part numbers (CPN) available in 100L LQFP (14x14x1.4mm) package.

Affected CPNs:

[JAON-23SJYM687_Affected_CPN_03012021.pdf](#)

[JAON-23SJYM687_Affected_CPN_03012021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of ASEM as an additional assembly site for ATSAM4C32CA-AU and ATSAM4C32CA-AUR catalog part numbers (CPN) available in 100L LQFP (14x14x1.4mm) package.

Pre Change:

Assembled at ASE using palladium coated copper (PdCu) bond wire, 2288A die attach, CEL-9510HFL mold compound and lead frame with paddle size 240x240mils.

Post Change:

Assembled at ASE using palladium coated copper (PdCu) bond wire, 2288A die attach, CEL-9510HFL mold compound and

lead frame with paddle size 240x240 mils or Assembled at ASEM using palladium coated copper with gold flash (CuPdAu) bond wire, YIZ8143 die attach, CEL-9240HF10AK-G1 mold compound and lead frame with paddle size 276x276 mils.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	ASE Group -Malaysia (ASEM)
Bond Wire material	PdCu	PdCu	CuPdAu
Die Attach material	2288A	2288A	YIZ8143
Mold compound material	CEL-9510HFL	CEL-9510HFL	CEL-9240HF10AK-G1
Lead frame material	C7025	C7025	C7025
Lead frame paddle size	240X240 mils	240X240 mils	276X276 mils
	See attached pre and post change comparison		

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ASEM as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date: April 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

[illegible]

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: **March 1, 2021:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-23SJYM687_Qual_Plan.pdf](#)

[PCN_JAON-23SJYM687_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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